

View Online at <https://aerobasegroup.com/nsn/8030-01-629-4132>

Physical Form:

Solid

Usage Design:

For extremely low thermal impedance at thinner bondline thicknesses (sometimes below 1 mil)

Curing Method:

Heat

Product Name:

Thermal grease

Special Features:

Silicone based thermal grease that conducts heat between hot component and a heat sink or enclosure; fills interface variable tolerances in electronics assemblies and heat sink applications; non curing, dispensable, highly conformable materials require no cure cycle, mixing or refrigeration; thermally stable and require virtually no compressive force to deform under assembly pressure; meet the need for high power applications requiring material with bond line thickness and high conductivity; ideal for rework and field repair situations; operating temp range-minus 55c to 200c

Color:

Gray, light

Material:

Silicone

Shelf Life:

N/a

Unit Of Measure:

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Demilitarization:

No

Fig:

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